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AN/"Semprius Inc": 27 patents.
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	PAT. NO.		Title
1	9,660,008	T	High-yield fabrication of large-format substrates with distributed, independent control elements
2	9,603,259	T	Methods for surface attachment of flipped active components
3	9,601,671	T	Optical systems fabricated by printing-based assembly
4	9,496,155	T	Methods of selectively transferring active components
5	9,443,883	T	Methods of forming printable integrated circuit devices and devices formed thereby
6	9,412,727	T	Printing transferable components using microstructured elastomeric surfaces with pressure modulated reversible adhesion
7	9,401,344	T	Substrates with transferable chiplets
8	9,362,113	T	Engineered substrates for semiconductor epitaxy and methods of fabricating the same
9	9,355,854	T	Methods of fabricating printable compound semiconductor devices on release layers
10	9,343,363	T	Through-silicon vias and interposers formed by metal-catalyzed wet etching
11	9,307,652	T	Methods for surface attachment of flipped active components
12	9,165,989	T	High-yield fabrication of large-format substrates with distributed, independent control elements
13	9,161,448	T	Laser assisted transfer welding process
14	9,142,468	T	Structures and methods for testing printable integrated circuits
15	9,117,940	T	Optical systems fabricated by printing-based assembly
16	9,049,797	T	Electrically bonded arrays of transfer printed active components
17	9,040,425	T	Methods of forming printable integrated circuit devices and devices formed thereby
18	8,934,259	T	Substrates with transferable chiplets
19	8,894,754	T	Breathing and desiccant regenerating cycle for reducing condensation in concentrator photovoltaic modules
20	8,889,485	T	Methods for surface attachment of flipped active componenets
21	8,877,648	T	Methods of forming printable integrated circuit devices by selective etching to suspend the devices from a handling substrate and devices formed thereby
22	8,722,458	T	Optical systems fabricated by printing-based assembly
23	8,506,867	T	Printing semiconductor elements by shear-assisted elastomeric stamp transfer
24	8,470,701	T	Printable, flexible and stretchable diamond for thermal management

25 8,261,660 T Vacuum coupled tool apparatus for dry transfer printing semiconductor elements
26 7,999,454 T OLED device with embedded chip driving
27 7,927,976 T Reinforced composite stamp for dry transfer printing of semiconductor elements

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